



BERGQUIST GAP FILLER TGF 1500

Known as BERGQUIST GAP FILLER 1500 October 2018

PRODUCT DESCRIPTION

A thermally conductive, liquid gap filler material.

Technology	Silicone
Appearance (cured)	Yellow
Appearance - Part A	Yellow
Appearance - Part B	White
Cure	Room temperature cure or Heat cure
Application	Thermal management,
	TIM (Thermal Interface Material)
Mix Ratio by weight:	1:1
Part A: Part B	
Mix Ratio by volume:	1:1
Part A: Part B	
Solids Content, %	100
Operating Temperature	-60 to 200°C
Range	

FEATURES AND BENEFITS

- Thermal Conductivity: 1.8 W/m-K
- Optimized shear thinning characteristics for ease of dispensing
- Excellent slump resistance (stays in place)
- Ultra-conforming, with excellent wet-out for low stress interface applications
- 100% solids no cure by-products
- Excellent low and high temperature mechanical and chemical stability

BERGQUIST GAP FILLER TGF 1500 is a two-part, high performance, thermally conductive liquid gap filling material, which features superior slump resistance and high shear thinning characteristics for optimized consistency and control during dispensing. The mixed system will cure at room temperature and can be accelerated with the addition of heat.

Unlike cured thermal pad materials, a liquid approach offers infinite thickness variations with little or no stress to the sensitive components during assembly. BERGQUIST GAP FILLER TGF 1500 exhibits low level natural tack characteristics and is intended for use in applications where a strong structural bond is not required.

As cured, BERGQUIST GAP FILLER TGF 1500 provides a soft, thermally conductive, form-in place elastomer that is ideal for fragile assemblies and filling unique and intricate air voids and gaps.

TYPICAL APPLICATIONS

- Automotive electronics (HEV, NEV, batteries)
- Telecommunications
- Computer and peripherals
- Between any heat-generating semiconductor and a heat sink

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, High shear, Capillary, ASTM D5099, mPa·s (cP): 3,000/ sec, Part A and B measured separately 25,000 Density, ASTM D792, g/cc 2.7 Pot Life @ 25°C , Parallel Plate Rheometer - Working life as liquid:

@ 60 minutes

@ 480 minutes

Shelf Life @ 25°C, days

180

TYPICAL CURE SCHEDULE

Cure Schedule

5 hours @ 25°C 10 minutes @ 100°C

Alternate Cure Schedule

3 days @ 25°C

30 minutes @ 100°C

Parallel plate rheometer, estimated time to read 90% cure.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

Hardness, Shore 00, Thirty second delay value, ASTM D2240	50
Heat Capacity, ASTM D1269, J/g-K	1.0
Flammability, UL 94	V-0

Electrical Properties

=100t110t1110p01t100		
Dielectric Strength, ASTM D149, V/mil	400	
Dielectric Constant , ASTM D150 @ 1,000 Hz	6.4	
Volume Resistivity ASTM D257_ohm-meter	1×10 ¹⁰	

Thermal Properties

Thermal Conductivity, ASTM D5470, W/(m-K) 1.8

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).



Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

CONFIGURATIONS AVAILABLE

BERGQUIST GAP FILLER TGF 1500 is available in the following configurations:

- Cartridges
- Kits
- With or without glass beads

STORAGE

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 5 to 25°C for a 6 month shelf life, in sealed containers with moisture barrier packaging.

Conversions

 $(^{\circ}C \times 1.8) + 32 = ^{\circ}F$ kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb/F N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Belgium NV, Henkel Electronic Materials NV, Henkel Nederland BV, Henkel Technologies France SAS and Henkel France SA please additionally note the following:

In case Henkel would be nevertheless held liable, on whatever legal ground, Henkel's liability will in no event exceed the amount of the concerned delivery.

In case products are delivered by Henkel Colombiana, S.A.S. the following disclaimer is applicable:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Corporation, Resin Technology Group, Inc., or Henkel Canada Corporation, the following disclaimer is applicable:

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits. The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

Trademark usage: [Except as otherwise noted] All trademarks in this document are trademarks and/or registered trademarks of Henkel and its affiliates in the U.S. and elsewhere.

Reference 2